

1A Avg.

400 Volts

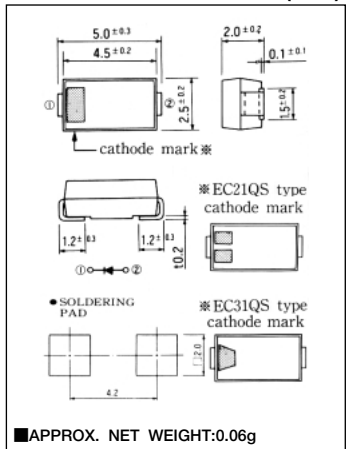
FRED

EC11FS4

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	400	V
非くり返しピーク逆電圧 Non-repetitive Peak Reverse Voltage	$V_{RSM}$	440	V
平均整流電流 Average Rectified Forward Current	$I_O$	Ta=25°C *1	0.76 A
		Ta=26°C *2	1 A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	1.57	A
サージ順電流 Surge Forward Current	$I_{FSM}$	20 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$	-40~+150	°C
保存温度範囲 Storage Temperature Range	$T_{stg}$	-40~+150	°C

OUTLINE DRAWING(mm)



電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$T_j=25^\circ\text{C}, V_{RM}=V_{RRM}$	—	—	20	$\mu\text{A}$
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$T_j=25^\circ\text{C}, I_{FM}=1\text{A}$	—	—	1.25	V
逆回復時間 Reverse Recovery Time	trr	$I_{FM}=1\text{A}, -di/dt=50\text{A}/\mu\text{s}, T_j=25^\circ\text{C}$	—	—	30	ns
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	Glass Epoxy Substrate Mounted *1		—	157 °C/W
			Alumina Substrate Mounted *2		—	108 °C/W

\*1:プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands=2×2mm, Both Sides)  
\*2:アルミナ基板実装/Alumina Substrate mounted (Soldering Lands=2×2mm, Both Sides)

定格・特性曲線

